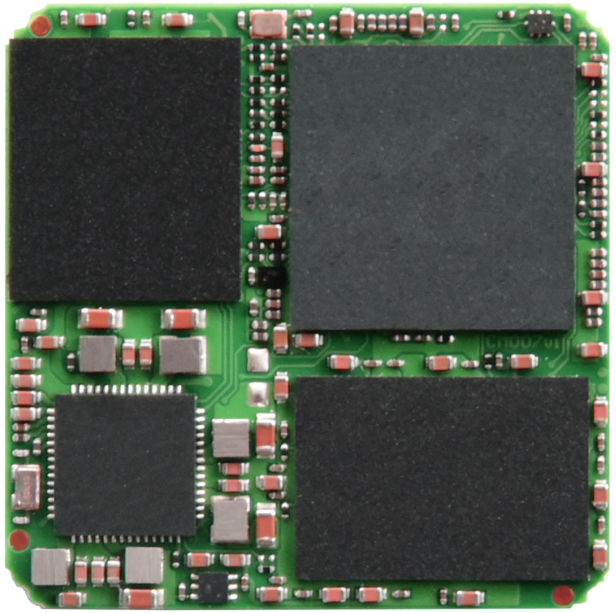
# Embedded Module with i.MX8M Mini

Open Standard Module™ - iesy i.MX8M Mini OSM-SF

## Technical Concept

- Processor: i.MX8M Mini Cortex-A53 Quad Core + Cortex-M4 MCU
- CPU Clock-Rate: 1.6 GHz (A53) + 400 MHz (M4)
- RAM: 1 GByte LPDDR4
- Flash-Memory: 16 GByte e-MMC 5.1
- Dimension: 30 mm x 30 mm
- Footprint: OSM Size-S
  Land Grid Array (LGA) with 332 contacts
- Supply: Single Supply 5VDC
- Temperature range:
  - Operating: -40 °C to +85 °C
  - Storage: -40 °C to +85 °C
- Power consumption: 1.3 W (typ.) / 3.4 W (max.)
- Features & Interfaces
  - 1 x LAN 10/100/1000 (RGMII)
  - 1x PCIe x1 (incl. I2C/SMBUS)
  - 2x USB 2.0 Client/Host/OTG
  - 1x MIPI DSI (4 Lanes)
  - 1x MIPI CSI (4 Lanes, incl. I2C)
  - 1x SD-Card, 1x SDIO/MMC (8 bit)
  - 1x QSPI, 1x SPI, 3x UART, 1x Debug-UART
  - 2x I2C, 1x I2S (2x TX/RX)
  - 24x GPIO, 3x PWM
  - 1x JTAG

iesy GmbH I Meinerzhagen I Germany I +49 (2354) 70655 0 I sales@iesy.com I www.iesy.com



## About OSM™

The Open Standard Modules™ specification was adopted by the SGeT e.V. in 2019. The new standard was developed to meet future requirements in terms of **flexibility**, **scalability**, but also **costs**. OSM™ solder-down modules can be **individually adapted** to the respective customer requirements. For this purpose, the individual modules can be made **available to the SMT process** by means of tray & reel packaging and processed automatically. The OSM™ series includes in total four different form factors.

**iesy.com/osm**